

**IN THE UNITED STATES PATENT AND TRADEMARK OFFICE**

Applicant: Alcoe *et al.*

Art Unit:

Serial No.:

Dkt. No.: END920010111US2

Filed:

Examiner:

Title: **MODULE WITH ADHESIVELY ATTACHED HEAT SINK**

Commissioner for Patents  
P.O. Box 1450  
Alexandria, VA 22313-1450

**Preliminary Amendment**

Sir:

Kindly enter this amendment prior to initial examination

**In the Specification:**

Page 1, between lines 1 and 2, insert: --This application is a divisional of Serial No.  
10/058,999; filed on 1/29/2002. *Pat. 6,744,132*

Please amend the paragraphs beginning on page 1, line 13 and ending on page 2, line 20  
as follows:

The present invention provides an electronic structure, comprising:  
a substrate;  
a semiconductor device electrically coupled to the substrate;  
a stiffener ring adhesively coupled to the substrate, wherein the stiffener ring surrounds  
the semiconductor; and  
a cover plate on a top surface of the semiconductor and on a top surface of the stiffener